

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

SS22B THRU SS210B

Product specification


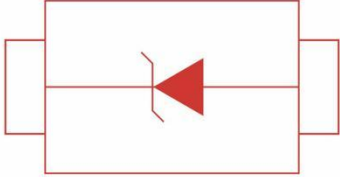
Features

- Ideal for surface mount applications
- Easy pick and place
- Built-in strain relief
- Low forward voltage drop

MECHANICAL DATA

- Case: Molded plastic
- Epoxy: UL 94V-0 rate flame retardant
- Metallurgically bonded construction
- Polarity: Color band denotes cathode end
- Mounting position: Any
- Weight: 0.093 grams

Reference News

PACKAGE OUTLINE	Pin Configuration
	
DO-214AA(SMB)	

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25 C ambient temperature unless otherwise specified .
 Single phase half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

TYPE NUMBER	SS22B	SS23B	SS24B	SS25B	SS26B	SS28B	SS29B	SS210B	UNITS	
Maximum Recurrent Peak Reverse Voltage	20	30	40	50	60	80	90	100	V	
Maximum RMS Voltage	14	21	28	35	42	56	63	70	V	
Maximum DC Blocking Voltage	20	30	40	50	60	80	90	100	V	
Maximum Average Forward Rectified Current See Fig. 1	2.0								A	
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	50								A	
Maximum Instantaneous Forward Voltage at 2.0A	0.55		0.70			0.85			V	
Maximum DC Reverse Current at Rated DC Blocking Voltage	0.1					0.02				mA
	5					2				mA
Typical Junction Capacitance (Note1)	170								pF	
Typical Thermal Resistance R _{JA} (Note 2)	75								C/W	
Operating Temperature Range T _J	-65 — +150								°C	
Storage Temperature Range T _{STG}	-65 — +150								°C	

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Ambient.

RATING AND CHARACTERISTIC CURVES (SS22 THRU SS210)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

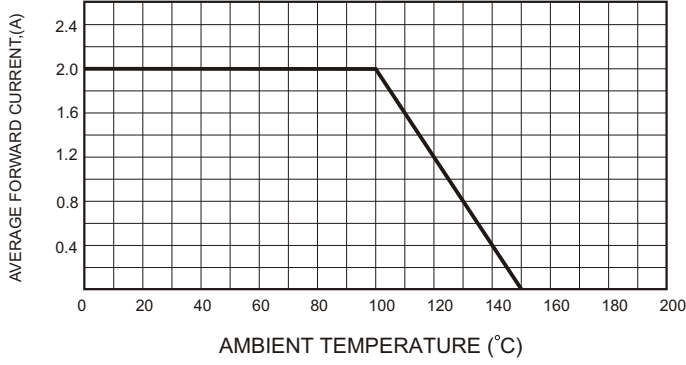


FIG.2-TYPICAL FORWARD CHARACTERISTICS

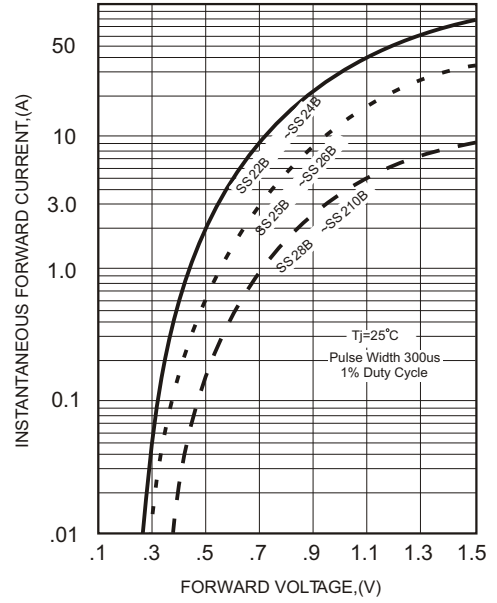


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

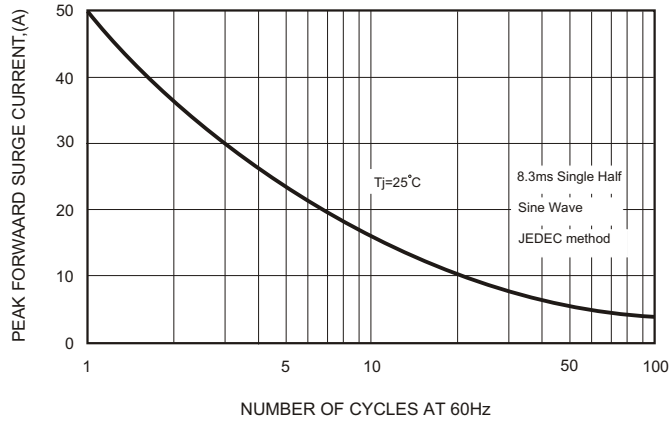


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

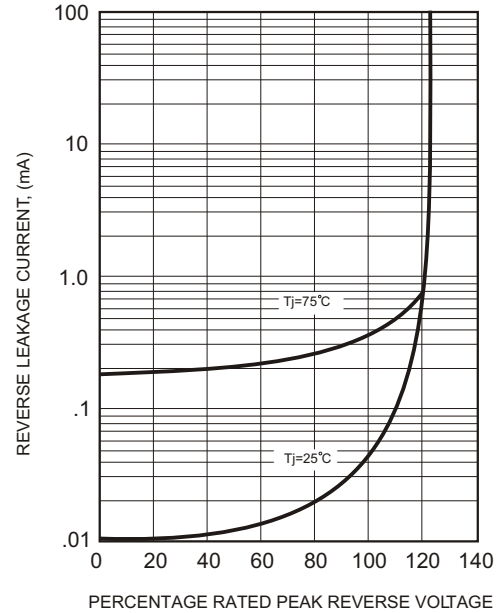
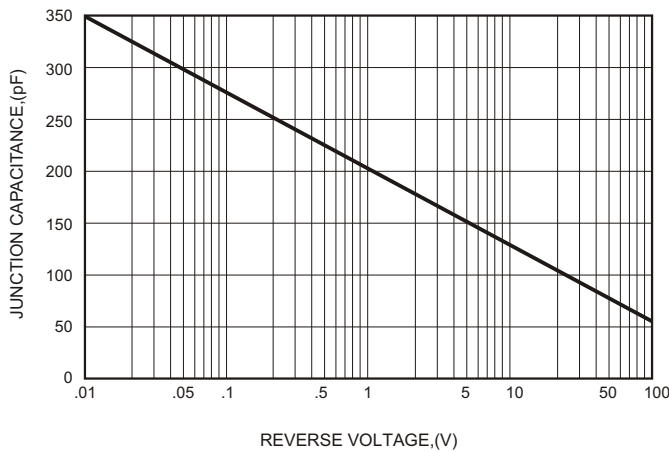
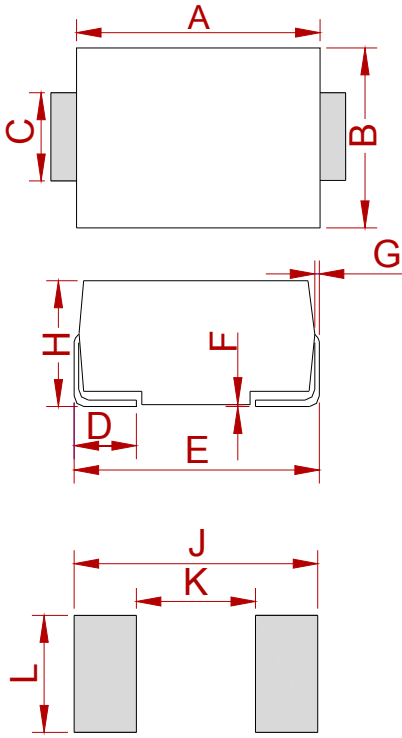


FIG.4-TYPICAL JUNCTION CAPACITANCE



PACKAGE MECHANICAL DATA



DO-214AA (SMB)

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.75	0.167	0.187
B	3.30	3.94	0.130	0.155
C	1.85	2.21	0.073	0.087
D	0.76	1.52	0.030	0.060
E	5.08	5.59	0.200	0.220
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.11	2.44	0.083	0.096
J	6.80		0.270	
K		2.60		0.100
L	2.40		0.090	

REEL SPECIFICATION

P/N	PKG	QTY
SS22B THRU SS210B	SMB	3000

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